L Number	Hits	Search Text	DB	Time stamp
1	1	("4383886").PN.	USPAT	2003/06/29 17:22
2	1	("4700467").PN.	USPAT	2003/06/29 17:22
3	60	wafer with (wafer and (joints or joint) and etch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:24
4	40	(wafer with (wafer and (joints or joint) and etch)) and (@ad<20001102)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:52
5	0	batch adj transfer adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:32
6	2670	transfer adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:32
7	2046	(transfer adj wafer) and (@ad<20001102)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 20:02
8	709	((transfer adj wafer) and (@ad<20001102)) and (etch or etchant or etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:12
9	16444	(mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:49
10	10897	((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:04
11	8810	(((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:20
12	1148	((((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor) and (bump or joint or joints or bumps)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:22
13	369	(((((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor) and ((bump or joint or joints or bumps) with (wafer or semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:22

14	531	(((((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor) and (bump or joint or joints or bumps)) and transfer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:39
15	201	(((((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor) and ((bump or joint or joints or bumps) with (wafer or semiconductor))) not ((((((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor) and (bump or joint or joints or bumps)) and transfer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:39
16	133	438/459.ccls. and ((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:02
17	94	(438/459.ccls. and ((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and (wafer or substrate))) and (@ad<20001102)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:53
18	11	5336634.URPN.	USPAT	2003/06/29 18:59
19	92	438/459.ccls. and ((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and soi)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:30
20	72	(438/459.ccls. and ((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and soi)) and (@ad<20001102)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:04
21	0	6455398.URPN.	USPAT	2003/06/29 19:08
22	0	6455398.URPN.	USPAT	2003/06/29 19:08
23	21	("5281834" | "5346848" | "5373184" | "5386137" | "5407856" | "5472914" | "5502316" | "5503704" | "5523602" | "5557120" | "5606186" | "5728623" | "5728624" | "5849627" | "5858855" | "5966622" | "6004867" | "6030884" | "6074892" | "6153495" | "6180496").PN.	USPAT	2003/06/29 19:08
24	63	438/458.ccls. and ((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and soi)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:37

25	63	(438/458.ccls. and ((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and soi)) not (("5281834" | "5346848" | "5373184" | "5386137" | "5407856" | "5472914" | "5502316" | "5503704" | "5523602" | "5557120" | "5606186" | "5728623" | "5728624" | "5849627" | "5858855" | "5966622" | "6004867" | "6030884" | "6074892" | "6153495" | "6180496").PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:44
26	4	((438/458.ccls. and ((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and soi)) not (("5281834" | "5346848" | "5373184" | "5386137" | "5407856" | "5472914" | "5502316" | "5503704" | "5523602" | "5557120" | "5606186" | "5728623" | "5728624" | "5849627" | "5858855" | "5966622" | "6004867" | "6030884" | "6074892" | "6153495" | "6180496").PN.)) and ((ball or bump or joint) and (@ad<20001102))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:32
27	36	438/458.ccls. and wafer and (ball or bump or joint) and (@ad<20001102)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:55
28	38	438/459.ccls. and wafer and (ball or bump or joint) and (@ad<20001102)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 20:04
29	32	(438/459.ccls. and wafer and (ball or bump or joint) and (@ad<20001102)) not (438/458.ccls. and wafer and (ball or bump or joint) and (@ad<20001102))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:44
31	21	((438/459.ccls. and wafer and (ball or bump or joint) and (@ad<20001102)) not (438/458.ccls. and wafer and (ball or bump or joint) and (@ad<20001102))) and ((etch or etching or etchant) with wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 20:01
32	1678	((etch or etching or etchant) with wafer) and indium	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 20:01
33	1207	(((etch or etching or etchant) with wafer) and indium) and (@ad<20001102)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 20:02
34	1078	((((etch or etching or etchant) with wafer) and indium) and (@ad<20001102)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 20:04
35	192	(((((etch or etching or etchant) with wafer) and indium) and (@ad<20001102)) and semiconductor) and (ball or bump or joint)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 20:05